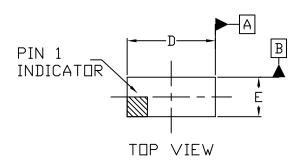
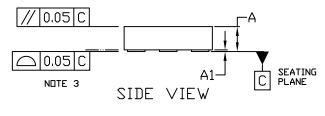


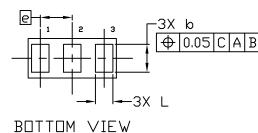
DSN3 0.76x0.34 (0301)

CASE 152BA **ISSUE A**

DATE 18 MAR 2021



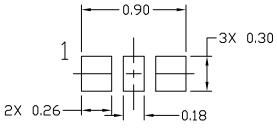




NOTES:

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 2009. CONTROLLING DIMENSION: MILLIMETERS
- COPLANARITY APPLIES TO ALL PADS

	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	0.17	0.20	0.23
A1	0.00		0.03
b	0.22	0.24	0.26
D	0.73	0.76	0.79
E	0.31	0.34	0.37
е	0.275 BSC		
L	0.13	0.15	0.17



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code

M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	DSN3 0.76x0.34 (0301)		PAGE 1 OF 1	

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